

01-24-2000

Atty Dkt. 5298-03600

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ereof.

To the Honorable Commissioner of Patents and Trademarks. 1

1. Name of conveying party(ies):

Gorley L. Lau

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):

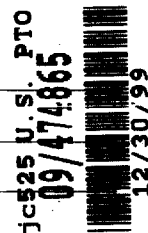
Name: Cypress Semiconductor Corp.

Internal Address: _____

Street Address: 3939 N. 1st Street

City San Jose State CA ZIP 95134

Additional name(s) & address(es) attached? Yes No



09/474865

3. Nature of Conveyance:

- Assignment
- Security Agreement
- Other
- Merger
- Change of Name

Execution Date: December 28, 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of this application is: December 28, 1999

A. Patent Application No.(s) B. Patent No.(s)

Additional numbers attached? Yes No

01/20/2000 TRADE1 00000003 09474865

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Kevin L. Daffer

Internal Address: Conley, Rose & Tayon, P.C.

Street Address: P.O. Box 398

City Austin State TX ZIP 78767-0398

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):\$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:
(Attach a duplicate copy of this page if paying by deposit account)

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9. Statement and Signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Kevin L. Daffer

Name of Person Signing
Reg. No. 34,146

Signature

December 30, 1999

Date

Total number of pages comprising cover sheet: 3

ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned, does hereby:

SELL, ASSIGN AND TRANSFER to CYPRESS SEMICONDUCTOR CORPORATION (the "Assignee"), having a place of business at 3939 North First Street, San Jose, CA, 95134 the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith, and is entitled "METHOD FOR FORMING VOID-FREE METALLIZATION IN AN INTEGRATED CIRCUIT", such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

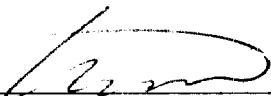
WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee; and

COVENANT AND AGREE that the above is and will be binding on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

FURTHER COVENANT that all statements made of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(Signature)  _____
Gorley L. Lau

Date: 12/28/99

Please direct all communication as follows:

Kevin L. Daffer
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